

PSR[®]-4000 AM Series

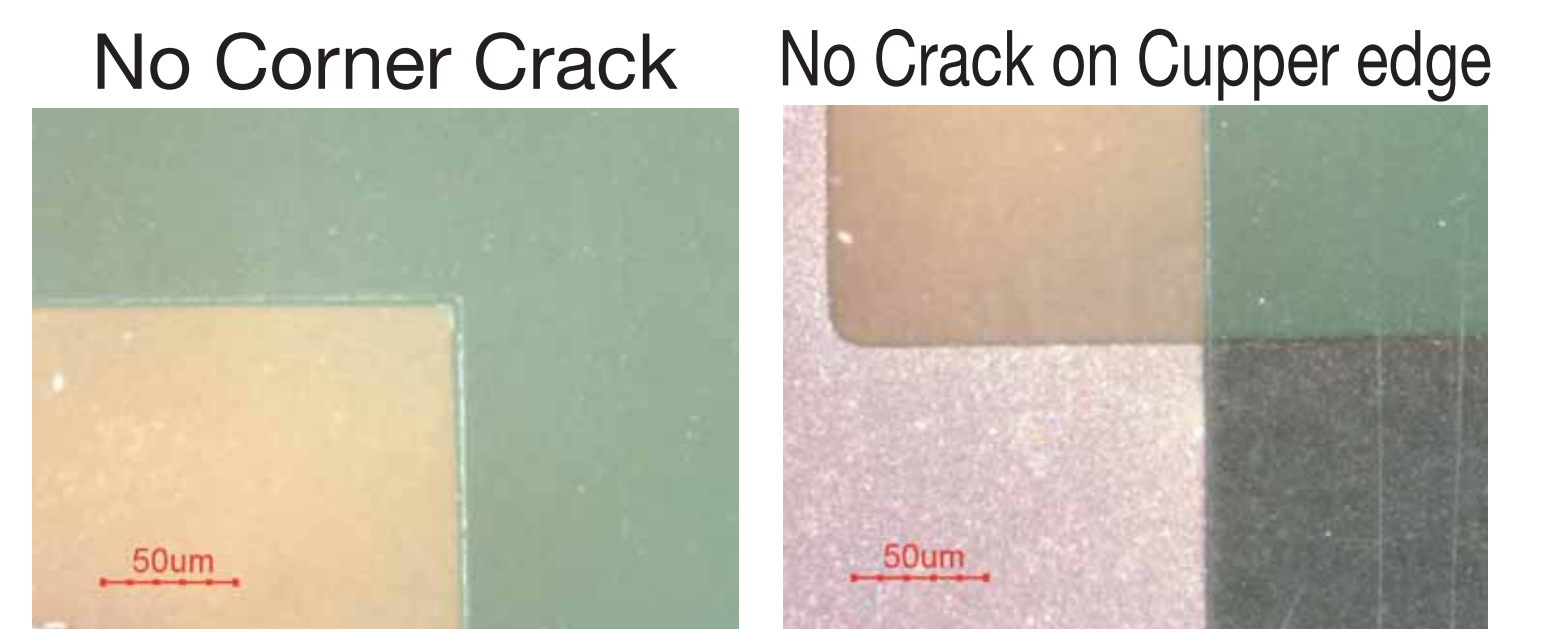
高信頼性ソルダーレジスト

High Reliability Photoimageable Solder Resist

新製品 New Products

・PSR[®]-4000 AM150 (Screen)

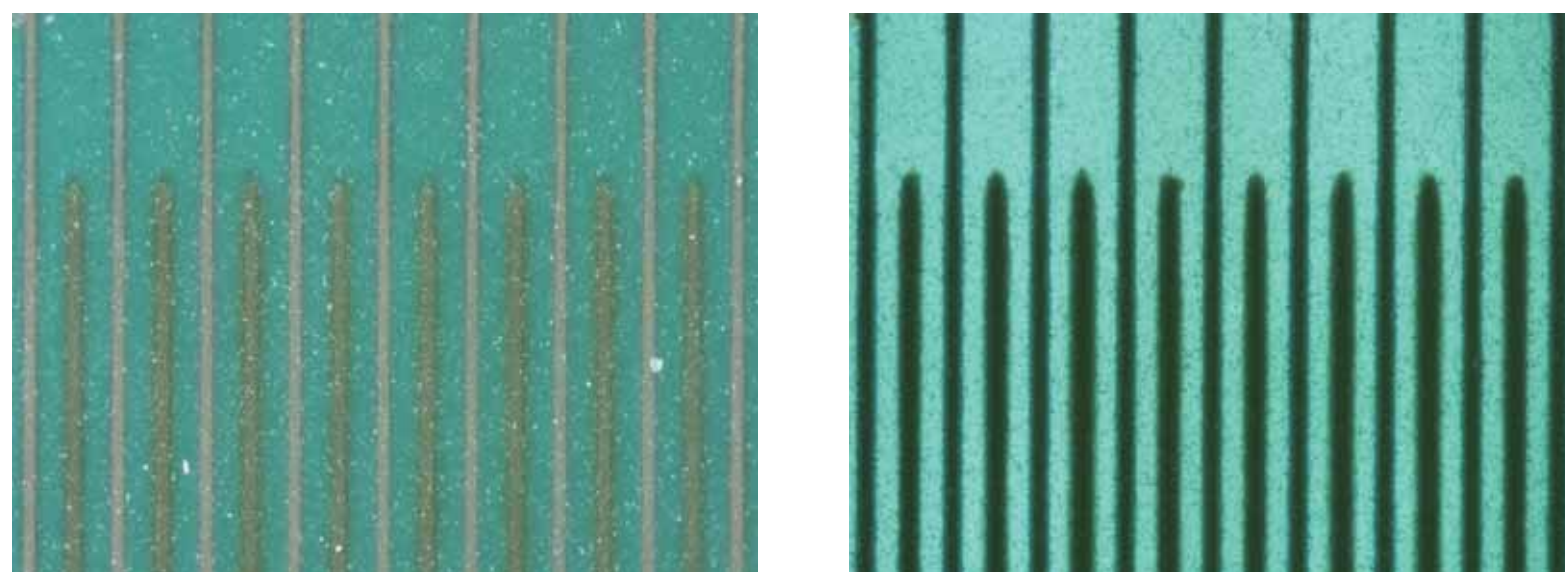
- 優れた冷熱衝撃サイクル耐性と高絶縁信頼性の両立
Well-balanced Thermal cycle resistance and Superior Migration resistance
- 絶縁信頼性 (121°C, 97%, L/S50/50μm, DC30V, 150h マイグレーション無し)
Insulation resistance(121°C, 97%, L/S50/50μm, DC30V, 150h Non migration)
- 冷熱サイクル耐性 (-40°C⇔125°C 1000cycle クラック無し)
Thermal cycle resistance(-40°C⇔125°C 1000cycle Non crack)
- 高感度 (200mJ/cm²)、高解像性
High Photo-sensitivity (200mJ/cm²), High resolution
- AM01NB以上の絶縁信頼性、AM10同等の冷熱サイクル耐性
Insulation resistance: High than AM01NB, Thermal cycle resistance: Equivalent to AM10



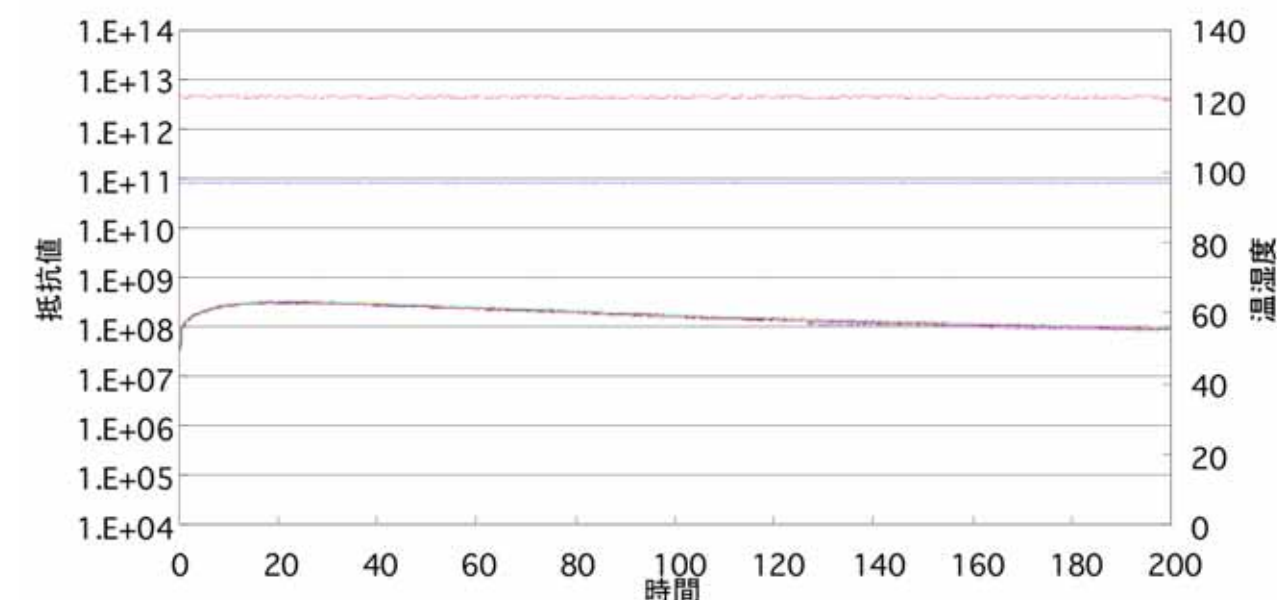
Thermal Cycle Test ; -40°C(30min.)⇔125°C(30min.)
Above 1000cycles

・PSR[®]-4000 AM100 (Screen)

- 優れたマイグレーション耐性と絶縁信頼性
Superior Migration resistance and Insulation resistance



PCBT after 200hrs (AM100)



L/S50/50μm DC30V PCBT槽内測定 (AM100)

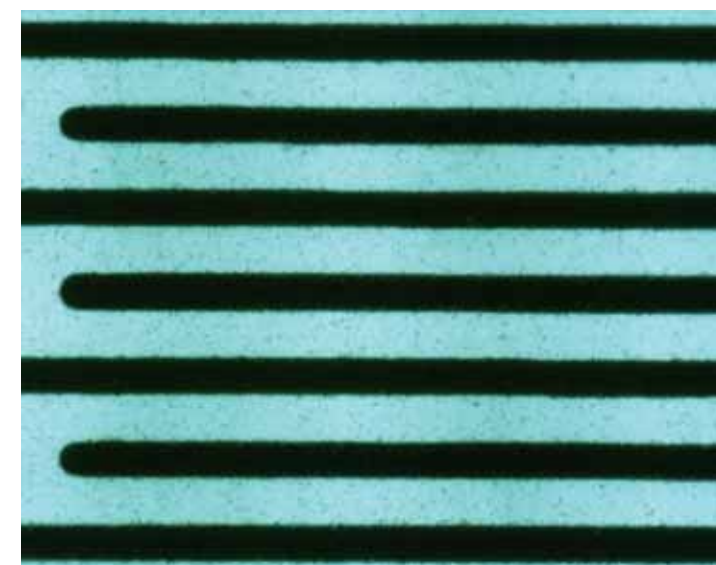
製品シリーズ Line-up

・PSR[®]-4000 AM01NB (Screen)

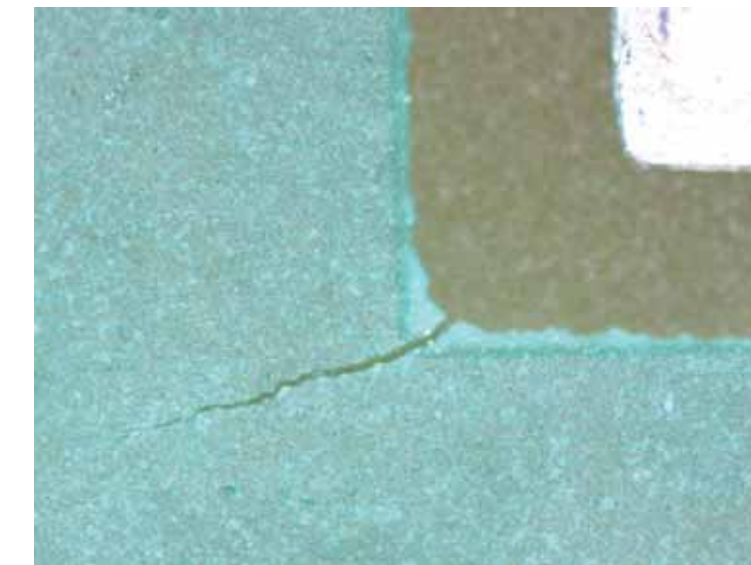
・PSR[®]-4000 AM02SP (Spray)

- 高マイグレーション耐性
Superior Migration resistance

HHBT after 3000hrs
(AM01NB)



PSR[®]-4000既存品
Conventional Solder Resist



PSR[®]-4000 AM10



Corner crack: Thermal Cycle -40°C(30min.)⇔140°C(30min.) Above 500cycles

・PSR[®]-4000 AM10 (Gloss, Screen)

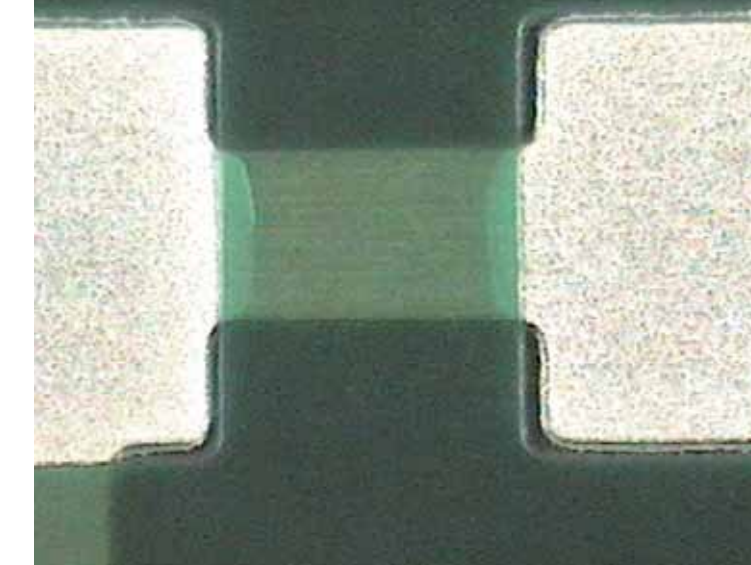
・PSR[®]-4000 AM10SP (Gloss, Spray)

- 冷熱サイクル耐性
Thermal cycle resistance

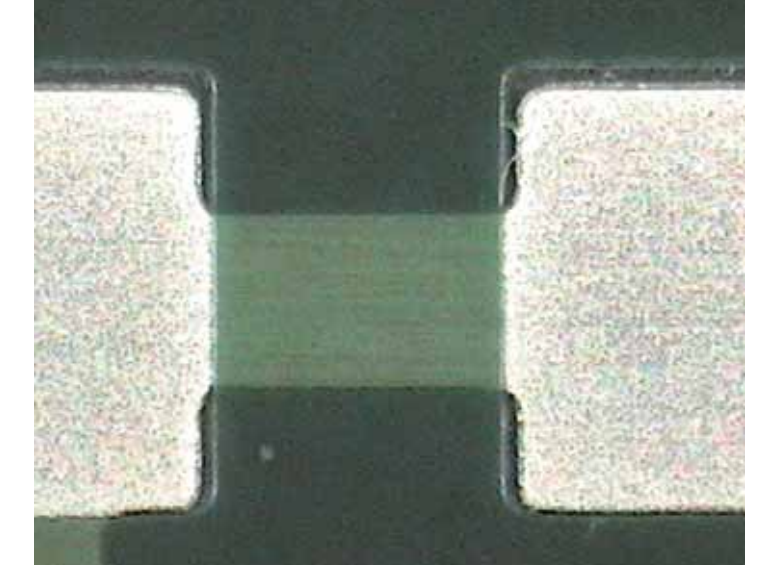
・PSR[®]-4000 AM Tin Series (Semi-Matte, Screen, Spray)

- 通常の前処理でも優れた錫めっき耐性
Excellent Immersion Tin resistance
(with conventional (mechanical) pretreatment copper)

PSR[®]-4000既存品
Conventional Solder Resist



PSR[®]-4000 AM Tin Series



すずめっき厚: 1μm以上 Tin deposit : above 1μm